Device and Method for Processing of Wafers

Abstract

The invention relates to a device for processing of substrates, especially wafers (15), with at least one pretreatment module (9), at least one aftertreatment module (11) and at least one primary treatment module (10), and the pretreatment module (9) and the aftertreatment module (11) can be switched as a lock for the primary treatment module (10), and a corresponding method for processing of substrates, especially wafers.

Figure 4